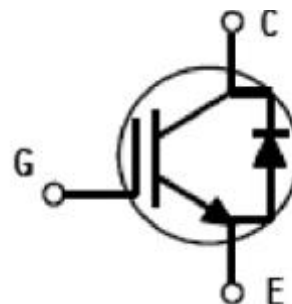


## 40A 1200V Trenchstop Insulated Gate Bipolar Transistor

### 1 Description

These Insulated Gate Bipolar Transistor used advanced trench and Fieldstop technology design, provided excellent  $V_{cesat}$  and switching speed, low gate charge. Which accords with the RoHS standard.

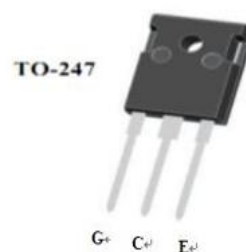


### 2 Features

- Low  $V_{cesat}$
- Low gate charge
- Excellent switching speed
- Easy paralleling capability due to positive temperature Coefficient in  $V_{cesat}$
- $T_{sc} \geq 6\mu s$
- Fast recovery full current anti-parallel diode

### 3 Applications

- Welding
- UPS
- Three-level Inverter



Type	Vces	Ic	Vcesat, Tj=25°C	Tjmax	Package
DGC40F120M2	1200V	40A (Tj=100°C)	1.7V (Typ)	175°C	TO-247-3L

### 4 Electrical Characteristics

#### 4.1 Absolute Maximum Ratings (Tc=25°C, unless otherwise specified)

Parameter	Symbol	Value	Units
Collector-to-Emitter Voltage	$V_{CES}$	1200	V
Gate-to-Emitter Voltage	$V_{GE}$	$\pm 30$	V
DC Collector current	$I_C$	Tc=25°C	80
		Tc=100°C	40
Pulsed Collector Current #1	$I_{CM}$	160	A
Diode forward current	$I_F$	Tc=25°C	80
		Tc=100°C	40
Diode Pulsed Current	$I_{FM}$	160	A
Short circuit withstand time, $V_{GE}=15V$ , $V_{CC}=600V$ , Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0s$ Tj=150°C	$T_{SC}$	6	$\mu s$
Power Dissipation	$P_{tot}$	Tc=25°C	388
		Tc=100°C	155
Junction Temperature Range	$T_j$	-45 ~ 175	°C
Storage Temperature Range	$T_{stg}$	-45 ~ 175	°C
Soldering temperature	$T_L$	260	°C

**4.2 Thermal Characteristics**

Parameter	Symbol	Rating	Units
IGBT Thermal Resistance Junction to Case-sink	$R_{thJC}$	0.32	$^{\circ}C/W$
IGBT Thermal Resistance Junction to Ambient	$R_{thJA}$	36.8	$^{\circ}C/W$
Diode Thermal Resistance Junction to Case-sink	$R_{thJC}$	0.61	$^{\circ}C/W$

**4.3 Electrical Characteristics** ( $T_c=25^{\circ}C$ , unless otherwise specified)

Parameter	Symbol	Conditions	Value			Units
			Min	Typ	Max	
<b>Static Characteristics</b>						
Collector-to-Emitter Breakdown Voltage	$V_{ces}$	$I_C=250\mu A, V_{GE}=0V, T_j=25^{\circ}C$	1200	--	--	V
Collector-to-Emitter Leakage Current	$I_{CES}$	$V_{CE}=1.2KV, V_{GE}=0V, T_j=25^{\circ}C$	--	--	25	$\mu A$
		$V_{CE}=1.2KV, V_{GE}=0V, T_j=175^{\circ}C$	--	--	10	mA
Gate-to-Emitter Leakage Current	$I_{GES}$	$V_{GE}=\pm 30V, V_{CE}=0V, T_j=25^{\circ}C$	--	--	$\pm 100$	nA
Gate Threshold Voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}, I_C=250\mu A$	4.5	5.5	6.5	V
Collector-emitter saturation voltage	$V_{cesat}$	$V_{GE}=15V, I_C=40A, T_j=25^{\circ}C$	--	1.7	2.1	V
		$V_{GE}=15V, I_C=40A, T_j=175^{\circ}C$	--	2.35	2.8	V
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{CE}=25V, V_{GE}=0V, f=1MHz, T_a=25^{\circ}C$	--	5896	--	pF
Output Capacitance	$C_{oss}$		--	143	--	
Reverse Transfer Capacitance	$C_{rss}$		--	38	--	
<b>IGBT Characteristics</b>						
Turn-on delay time	$t_d(on)$	$V_{CE}=600V, I_C=40A, R_g=10\Omega, V_{GE}=15V, \text{感性负载}, T_c=25^{\circ}C$	--	30	--	nS
Rise time	$t_r$		--	55	--	nS
Turn-off delay time	$t_d(off)$		--	200	--	nS
Fall time	$t_f$		--	250	--	nS
Turn-on energy	$E_{on}$		--	1.3	--	mJ
Turn-off energy	$E_{off}$		--	2.4	--	mJ
Total switching energy	$E_{ts}$		--	3.7	--	mJ
Turn-on delay time	$t_d(on)$	$V_{CE}=600V, I_C=40A, R_g=10\Omega, V_{GE}=15V, \text{感性负载}, T_c=175^{\circ}C$	--	38	--	nS
Rise time	$t_r$		--	60	--	nS
Turn-off delay time	$t_d(off)$		--	244	--	nS
Fall time	$t_f$		--	378	--	nS
Turn-on energy	$E_{on}$		--	1.5	--	mJ
Turn-off energy	$E_{off}$		--	3.3	--	mJ
Total switching energy	$E_{ts}$		--	4.8	--	mJ
Gate charge	$Q_g$	$V_{CE}=600V, I_C=40A, V_{GE}=15V$	--	198	--	nC

Diode Characteristic						
Diode forward voltage	$V_F$	$I_F=40A, T_j=25^\circ C$	--	3.3	4.8	V
		$I_F=40A, T_j=175^\circ C$	--	2.6	3.6	V
Diode reverse recovery time	$t_{rr}$	$I_F=40A,$ $di/dt=200A/\mu s,$ $V_R=400V$	--	86	--	ns
Diode peak reverse recovery current	$I_{rrm}$		--	5.8	--	A
Diode reverse recovery charge	$Q_{rr}$		--	280	--	nC

Notes:

#1 Pulse duration is limited by  $T_{j,max}$

### 5 Typical Characteristic Curves

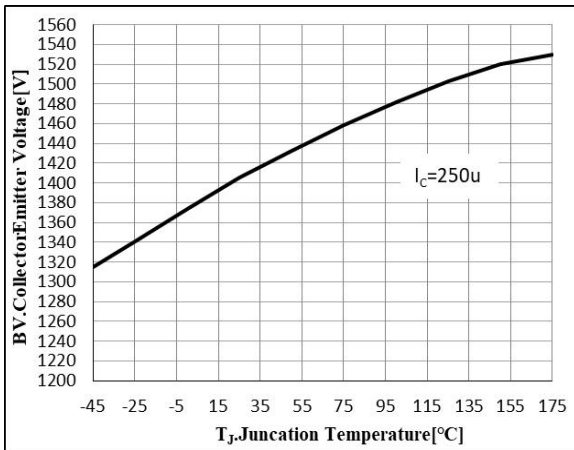


Fig1. Collector-to-Emitter Breakdown Voltage of temperature characteristic

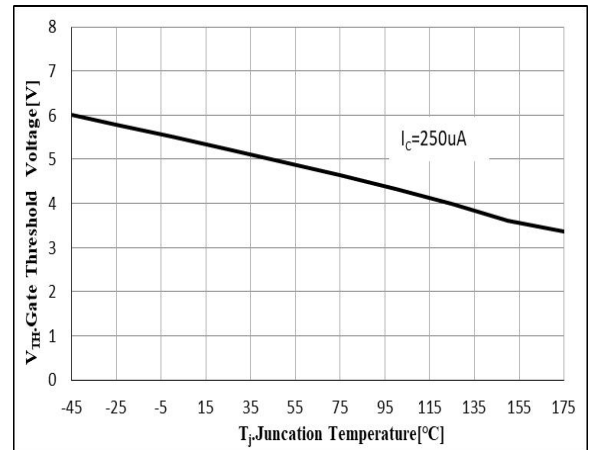


Fig2. Gate-to-Emitter Threshold Voltage of temperature characteristic

5 Typical Characteristic Curves(Continue)

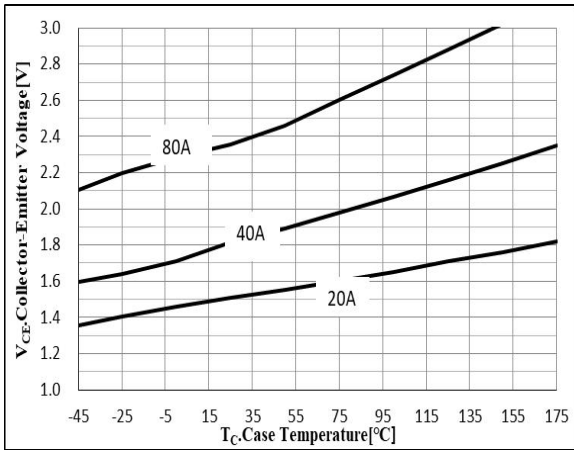


Fig3. Collector-emitter saturation voltage of temperature characteristic

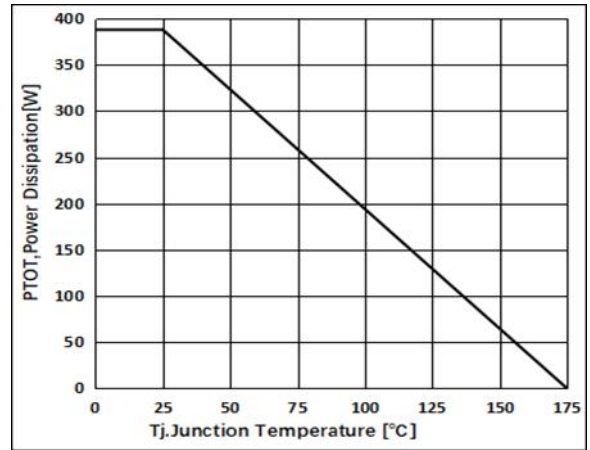


Fig4. Power Dissipation

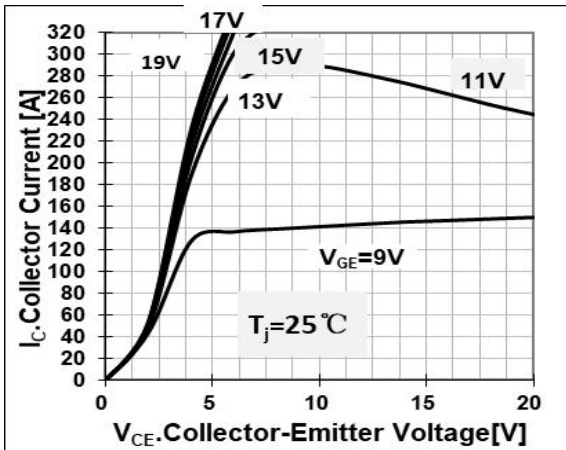


Fig5. Typical output characteristic

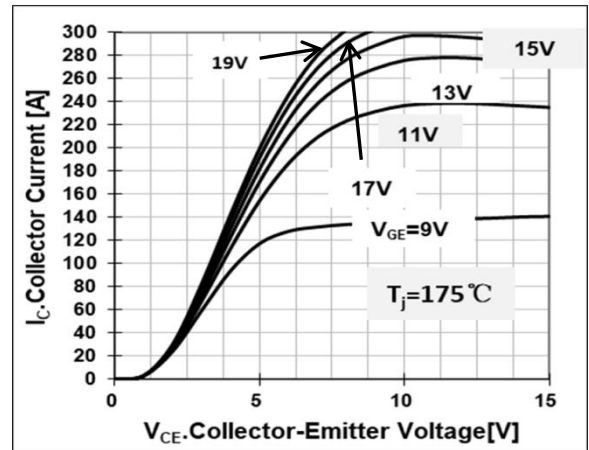


Fig6. Typical output characteristic

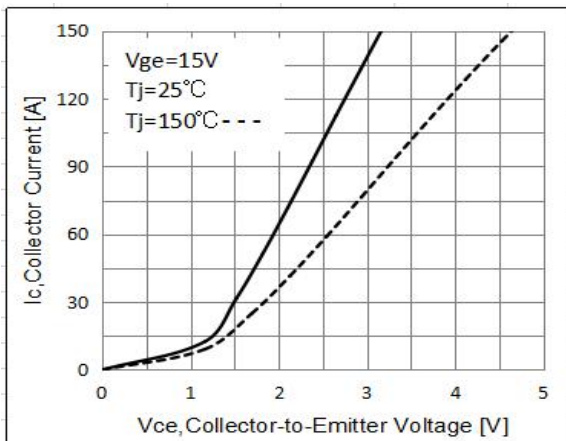


Fig7. Collector-emitter saturation voltage

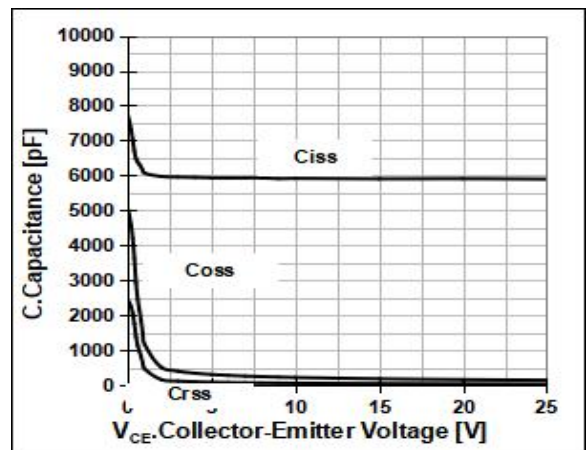


Fig8. Typical capacitance as a function of collector-emitter voltage

**5 Typical Characteristic Curves(Continue)**

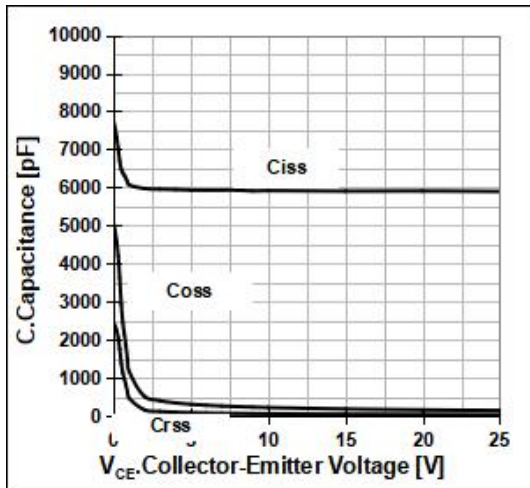


Fig9. Typical capacitance as a function of collector-emitter voltage

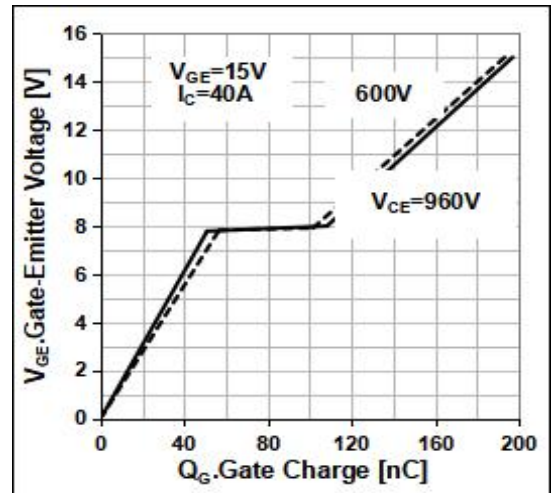


Fig10. Typical gate charge

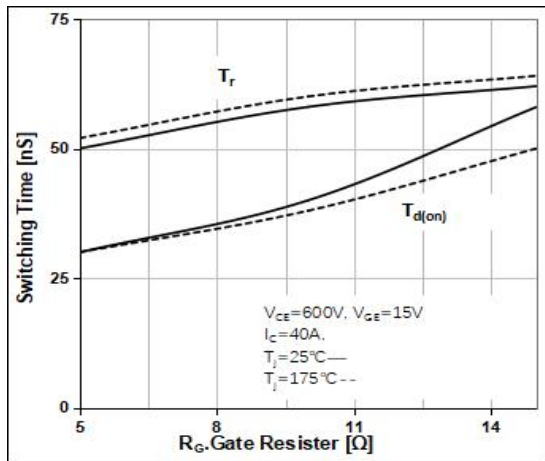


Fig11. Typical switching times as a function of gate resistor

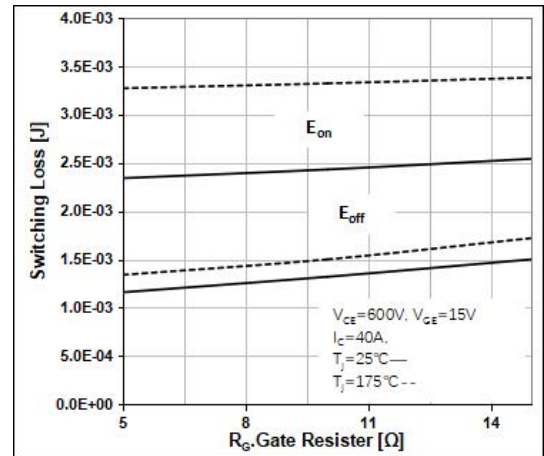


Fig12. Typical switching energy losses as a function of gate resistor

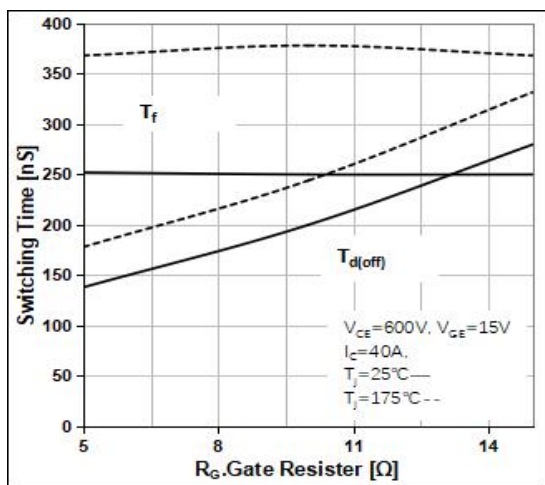


Fig13. Typical switching times as a function of gate resistor

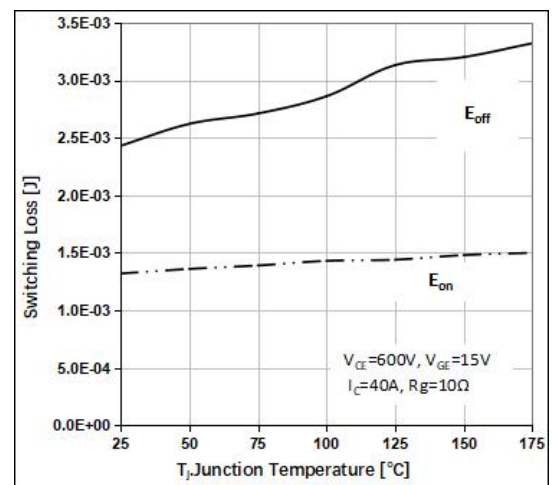


Fig14. Typical switching energy losses as a function of Junction Temperature

**5 Typical Characteristic Curves(Continue)**

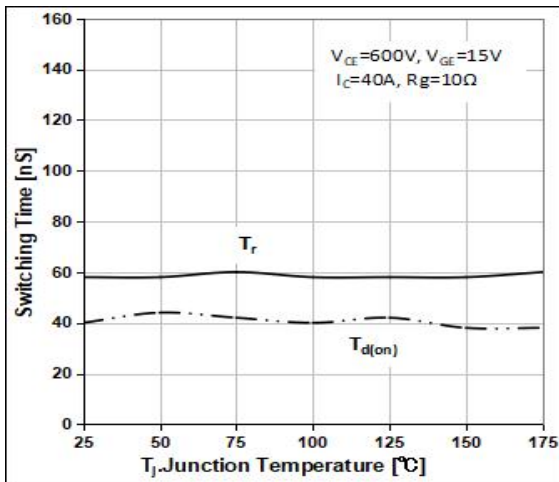


Fig15. Typical switching times as a function of Junction Temperature

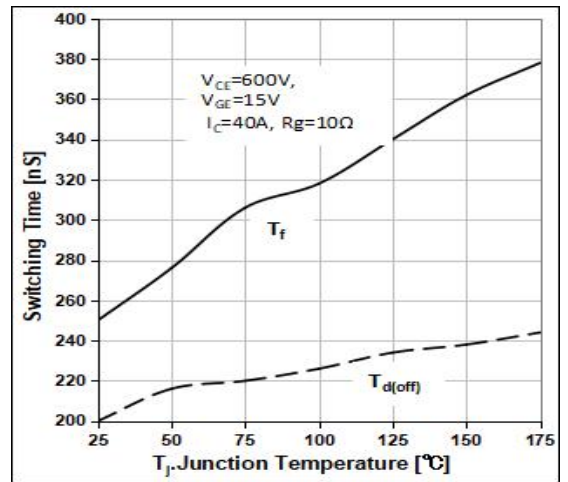


Fig16. Typical switching times as a function of Junction Temperature

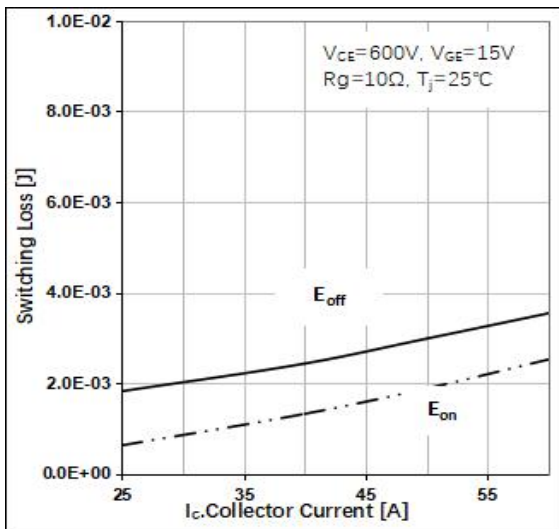


Fig17. Typical switching energy losses as a function of Collector Current

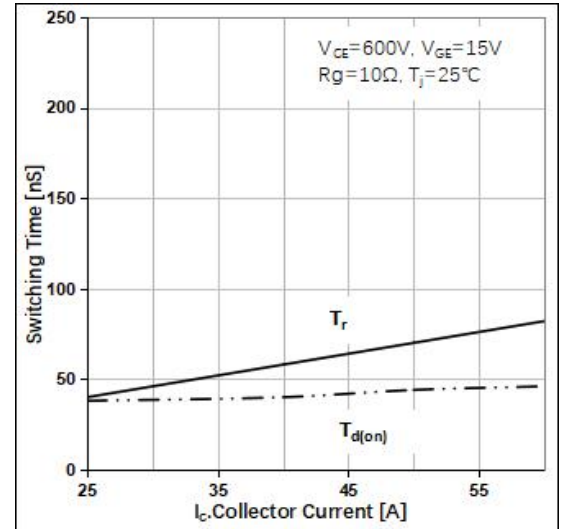


Fig18. Typical switching times as a function of Collector Current

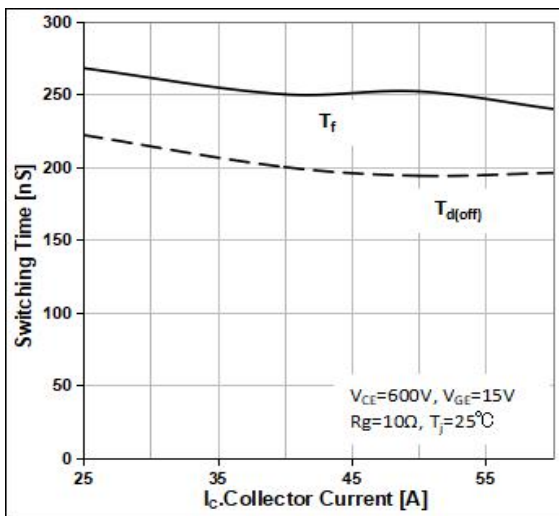


Fig19. Typical switching times as a function of Collector Current

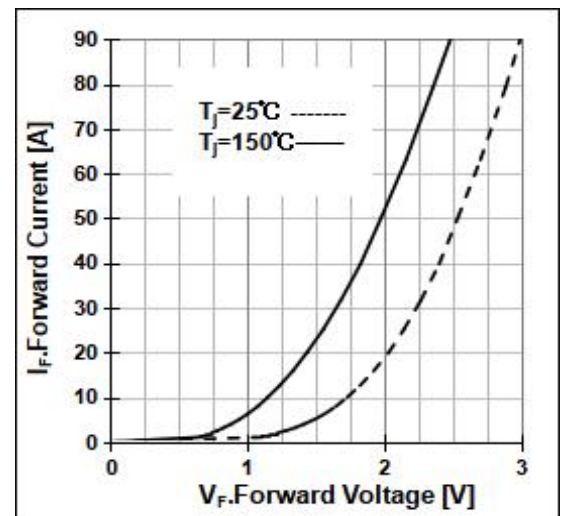


Fig20. Typical diode forward current as a function of forward voltage

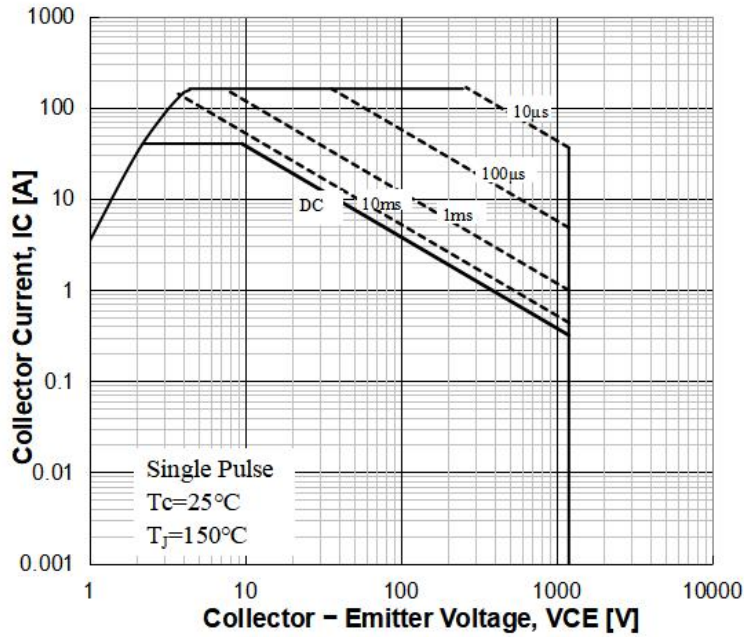


Fig21. Forward bias safe operating area

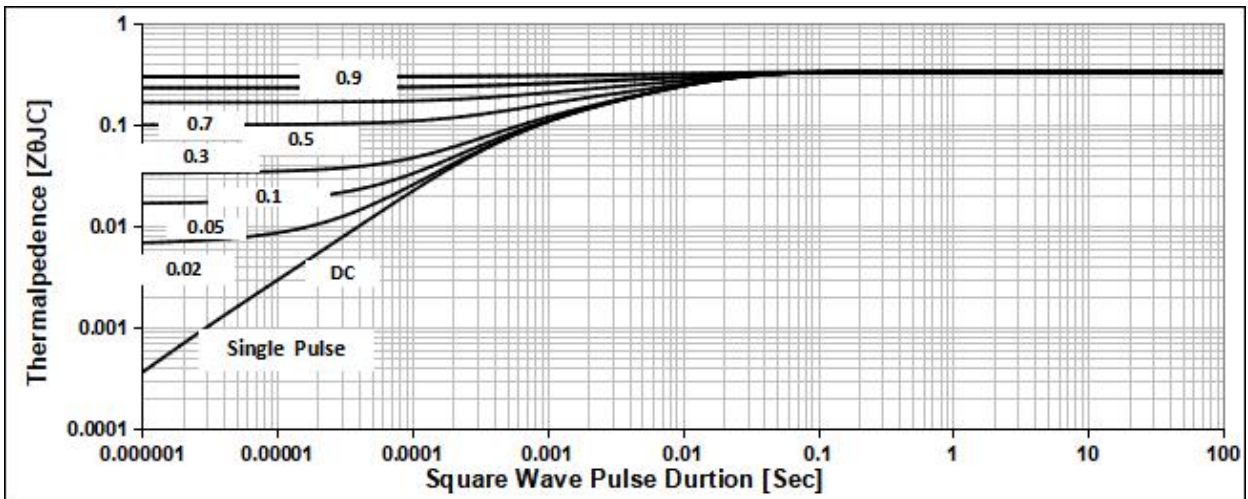


Fig22. IGBT transient thermal resistance

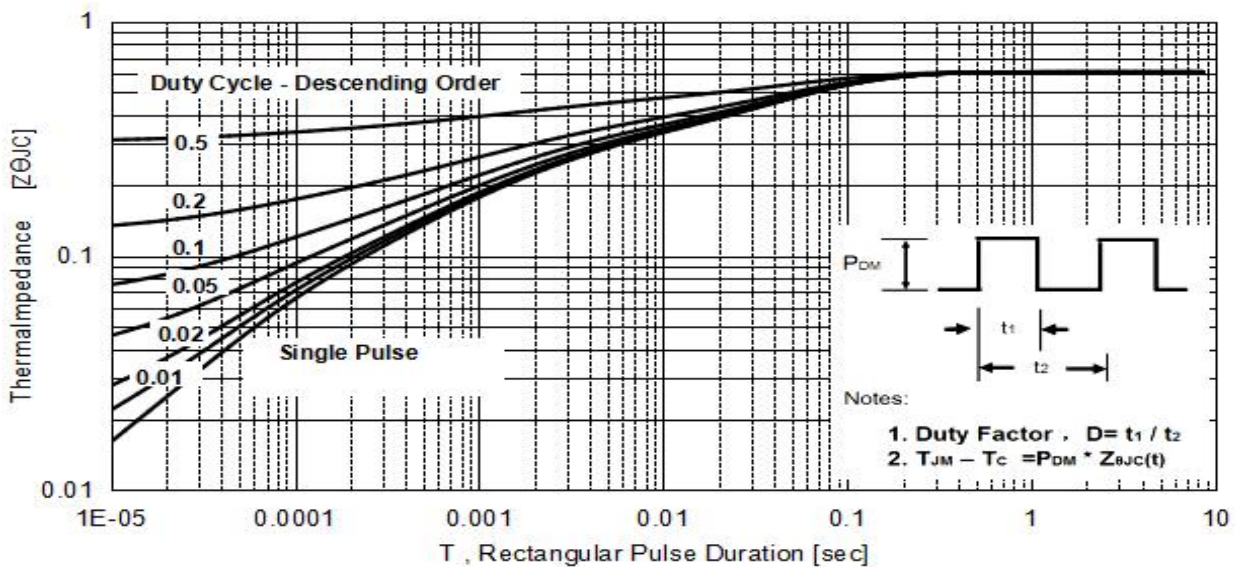
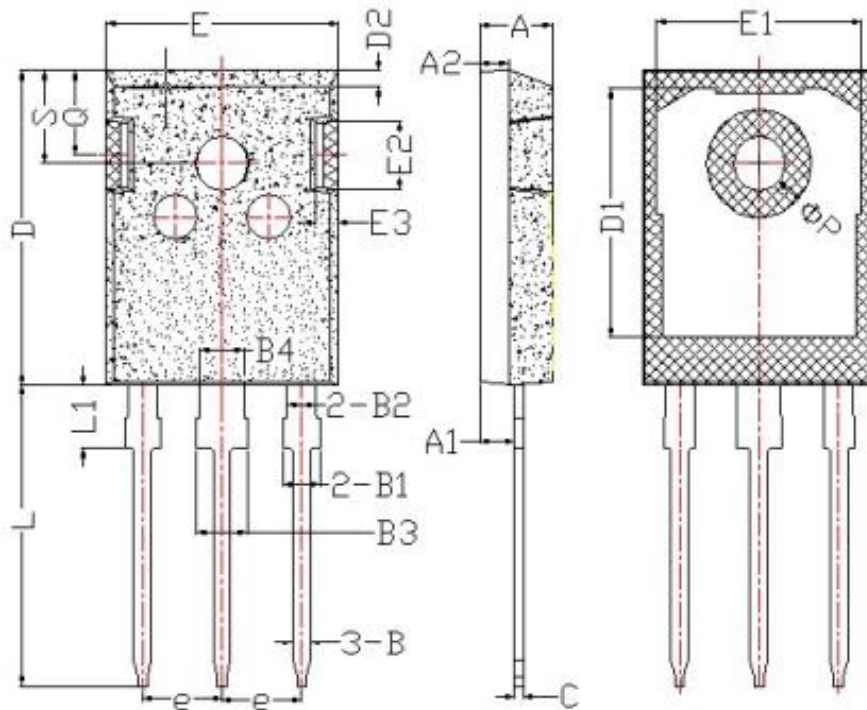


Fig23. Diode transient thermal resistance

6 Dimensions (TO-247)



项 目	规范(mm)		项 目	规范(mm)	
	MIN	MAX		MIN	MAX
A	4.60	5.20	E	15.50	16.10
A1	2.20	2.60	E1	13.00	14.70
B	0.90	1.40	E2	3.80	5.30
B1	1.75	2.35	E3	0.80	2.60
B2	1.75	2.15	e	5.20	5.70
B3	2.80	3.35	L	19.00	20.50
B4	2.80	3.15	L1	3.90	4.60
C	0.50	0.70	ΦP	3.30	3.70
D	20.60	21.30	Q	5.20	6.00
D1	16.00	18.00	S	5.80	6.60



## 7 Attentions

- Jiangsu Donghai Semiconductor Technology CO.,LTD. reserves the right to change the specification without prior notice! The customer should obtain the latest version of the information before making the order and verify that the information is complete and up to date.
- It is the responsibility of the purchaser for any failure or failure of any semiconductor product under certain conditions. It is the responsibility of the purchaser to comply with safety standards and to take safety measures in the system design and machine manufacturing of Donghai products in order to avoid potential risk of failure. Injury or property damage.
- Product promotion is endless, our company will be dedicated to provide customers with better products.

## 8 Appendix

Revision history:

Date	REV.	Description	Page
2023.6.21	1.0	Original	